LIQUID CRYSTAL DISPLAY MODULE

Product Specification

CUSTOMER	**Standard**
CUSTOMER PART NUMBER	
PRODUCT NUMBER	**DMT050WVNXCMI-1A**

Authorised By	Created By
Luo Luo	**Eric Wan**
Date: 20-Jan-17	Date: 20-Jan-17

TABLE OF CONTENTS

REVISION RECORD

Rev.	Date	Page	Chapt.	Comment	ECN no.
1.0	20-Jan-17			Initial Release	ECN8017

1 MAIN FEATURES

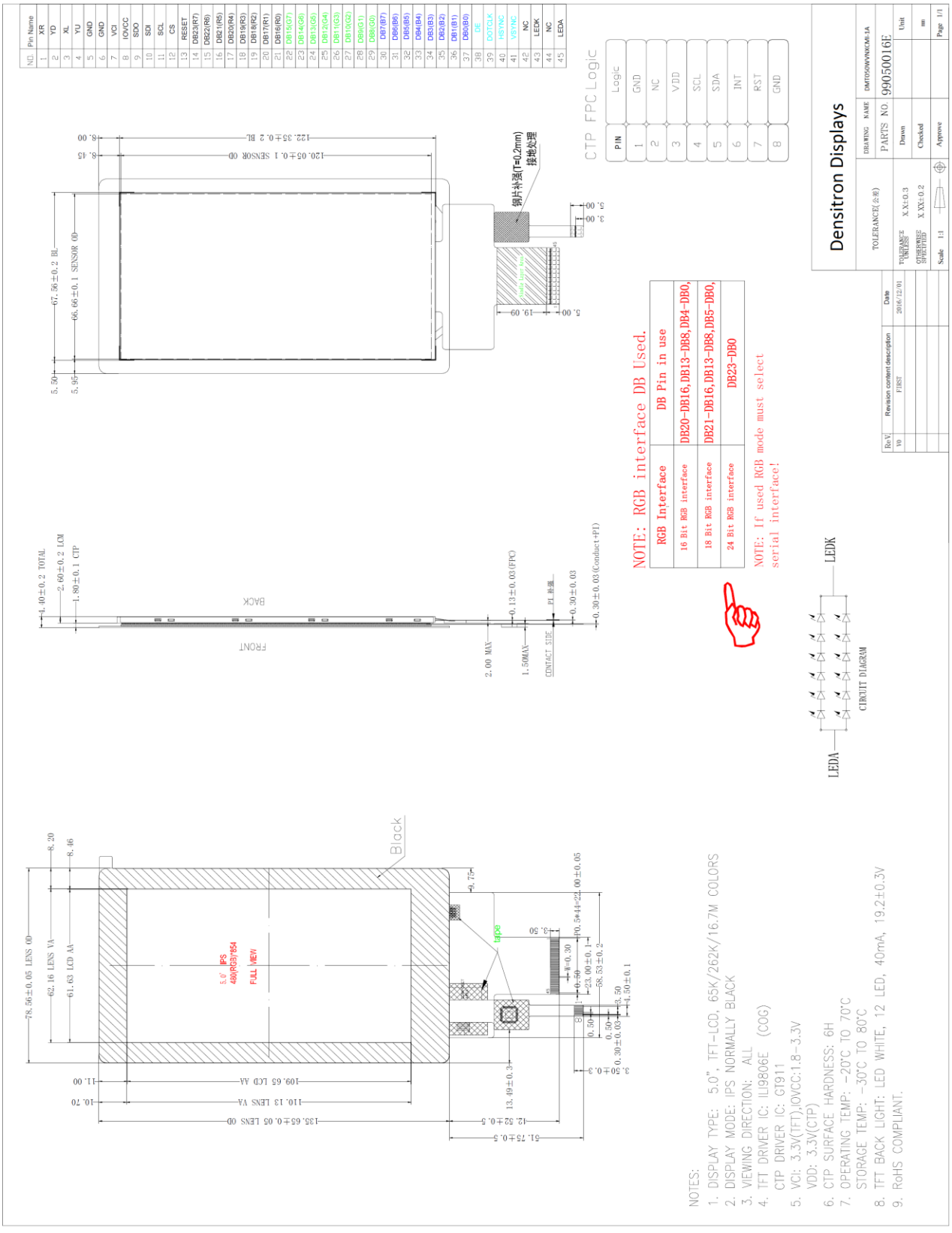
ITEM	CONTENTS
Screen Size	5.0” Diagonal
Display Format	480 x RGB x 854 Dots
N° of Colour	65K/262K/16.7M
TFT Active Area	61.63 mm (H) x 109.65 mm (V)
PCT View Area	62.16 mm (H) x 110.13 mm (V)
LCD Type	TFT
Mode	IPS Transmissive / Normally Black
Viewing Direction	Full view
TFT Interface	3-line SPI + 16/18/24-bit RGB interface
PCT Interface	I2C
TFT Driver IC	ILI9806E or equivalent
PCT Driver IC	GT911
Simultaneous Touch Points	5
Backlight Type	LED
Operating Temperature	-20°C ~ +70°C
Storage Temperature	-30°C ~ +80°C
RoHS compliant	Yes

2 MECHANICAL SPECIFICATION

2.1 MECHANICAL CHARACTERISTICS

ITEM	CHARACTERISTIC	UNIT
Display Format	480 x RGB x 854 Dots	Dots
Overall Dimensions	78.56 mm (H) x 135.65 mm (V) x 4.40 mm (D)	mm
Active Area	61.56 mm (H) x 109.53 mm (V)	mm
pixel Pitch	0.128 (H) x 0.128 (V)	mm
Weight	45	g

2.2 MECHANICAL DRAWING



3 ELECTRICAL SPECIFICATION

3.1 ABSOLUTE MAXIMUM RATINGS

3.1.1 TFT

Item	Symbol	Condition	Min	Max	Unit	Note
Power Supply Voltage	VCI	Ta=25˚C	-0.3	4.6	V	
Digital Interface Supply Voltage	IOVCC	Ta=25˚C	-0.3	4.6	V	
Operating Temperature	TOP		-20	70	°C	1
Storage Temperature	TST		-30	80	°C	1,2,3

Note 1. 90 % RH Max for Ta<50 °C, and 60% RH for Ta≥50°C.

Note 2. In case of below 0°C, the response time of liquid crystal (LC) becomes slower and the colour of panel becomes darker than normal one. Level of retardation depends on temperature, because of LC's characteristic.

Note 3. Only operation is guaranteed at operating temperature. Contrast, response time, another display quality are evaluated at +25°C.

3.1.2 PCT

Item	Symbol	Condition	Min	Max	Unit	Note
Power Supply Voltage	VDD	Ta=25˚C	2.66	3.47	V	4
Operating Temperature	TOP		-20	70	°C	-
Storage Temperature	TST		-30	80	°C	-

Note 4. If used beyond the absolute maximum ratings, GT911 may be permanently damaged. It is strongly recommended that the device be used within the electrical characteristics in normal operations. If exposed to the condition not within the electrical characteristics, it may affect the reliability of the device.

3.2 DC ELECTRICAL CHARACTERISTICS

3.2.1 TFT

Item	Symbol	Condition	Min	Typ	Max	Unit	Note
Supply Voltage	VCI		3.0	3.3	4.2	V	
Digital Interface Supply Voltage	IOVCC		1.8	3.3	3.6	V	
Input Voltage for Logic	VIH		0.7V_{CI}	-	V_{CI}	V	
	VIL		GND	-	0.3 V_{CI}	V	
Output Voltage for Logic	VOH		0.8V_{CI}	-	V_{CI}	V	
	VOL		GND	-	0.2V_{CI}	V	
Current Consumption	ICC		-	30	-	mA	1

Note 1: The specified power consumption is under the conditions of VCI=3.3V, FV=60Hz.

3.2.2 PCT

Item	Symbol	Condition	Min	Typ	Max	Unit	Note
Supply Voltage	VDD		2.8	-	3.3	V	
Input Voltage for Logic	VIH		0.75VDDIO	-	VDDIO+ 0.3	V	
	VIL		-0.3	-	0.25VDDIO	V	
Output Voltage for Logic	VOH		0.85VDDIO	-	-	V	
	VOL		-	-	0.15VDDIO	V	
Normal operation mode Current Consumption	IOPR		-	8	14.5	mA	
Green mode Current Consumption	IMON		-	3.3	-	mA	
Sleep mode Current Consumption	ISLP		70	-	120	uA	

3.3 INTERFACE PIN ASSIGNMENT

3.3.1 LCM PIN ASSIGNMENT

Pin NO.	Symbol	Function
1	XR	Not Connected
2	YD	Not Connected
3	XL	Not Connected
4	YU	Not Connected
5	GND	Ground
6	GND	
7	VCI	Analogue power supply 3.3V.
8	IOVCC	I/O power supply voltage (1.8V~3.3V)
9	SDO	Serial data output pin in serial bus system interface. If not used, please leave this pin open.
10	SDI (SDA)	Serial data input pin used for the SPI Interface. SDI : Serial data input pin SDA : Serial data input/output bidirectional pin
11	SCL	Serial Clock Input
12	CSX	Chip select signal. Low: chip can be accessed; High: chip cannot be accessed. If not used, please connect to GND.
13	RESX	Reset pin, active low
14-37	DB23-DB16 (R7-R0) DB15-DB8 (G7-G0) DB7-DB0 (B7-B0)	24-bit bi-directional data bus. 24-bit bus: use DB23-DB0 16-bit bus: use DB20-DB16, DB13-DB8, DB4-DB0 18-bit bus: use DB21-D16, DB13-DB8, DB5-DB0 Please connect unused pins to GND.
38	DE	Data Enable signal for RGB (DPI) I/F mode. Low : access enabled
39	DOTCLK	Pixel clock signal for RGB (DPI) I/F mode.
40	HSYNC	Line synchronizing signal for RGB (DPI) I/F mode.
41	VSYNC	Frame synchronizing signal for RGB (DPI) I/F mode.

Pin NO.	Symbol	Function
42	NC	Not connected
43	LEDK	Cathode pin of backlight
44	NC	Not connected
45	LEDA	Anode pin of backlight

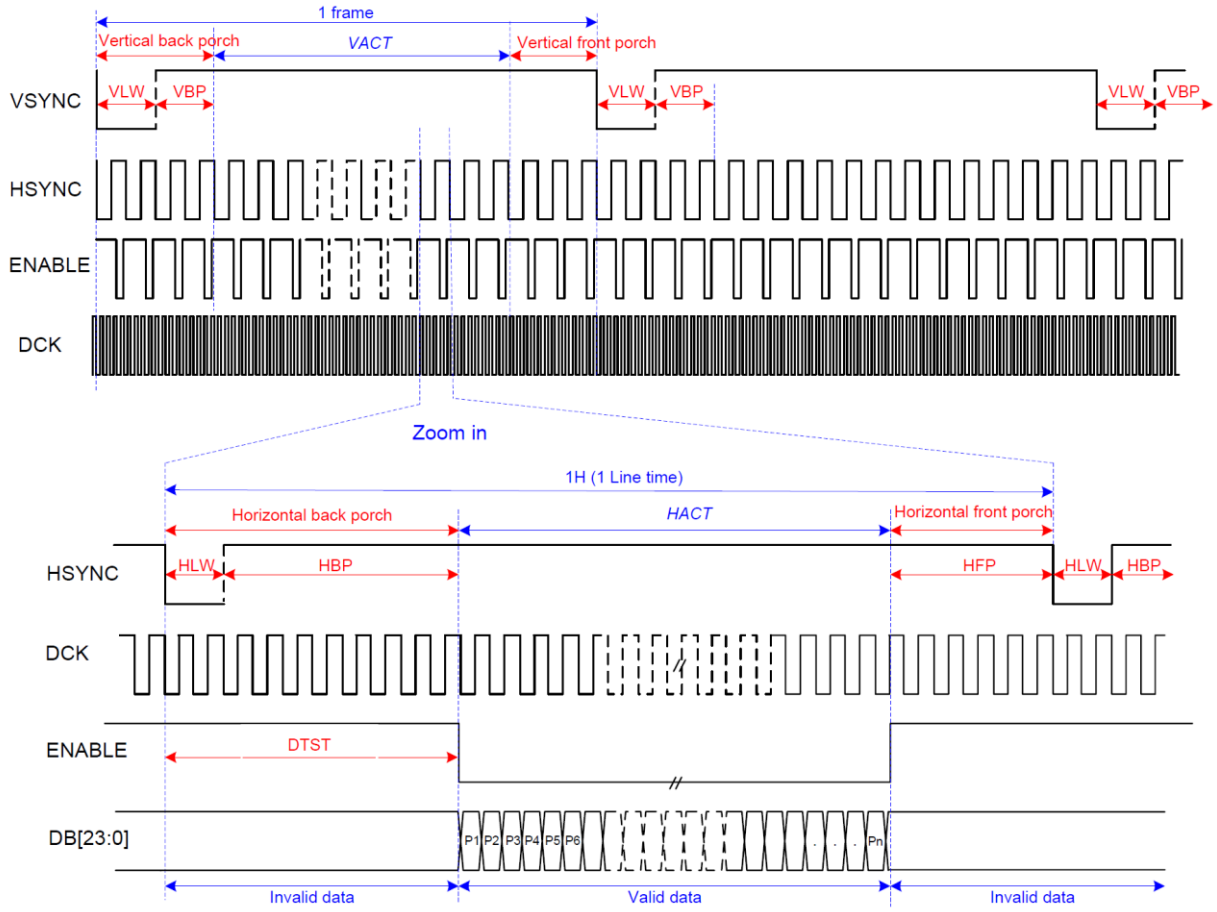
3.3.2 PCT PIN ASSIGNMENT

Pin NO.	Symbol	Function
1	GND	Ground
2	NC	Not connected
3	VDD	Supply voltage
4	SCL	I2C clock input
5	SDA	I2C data input and output
6	INT	External interrupt to the host
7	RST	External Reset, Low is active
8	GND	Ground

3.4 TIMING CHARACTERISTICS

Please refer to IC ILI9806E datasheet for more information

3.4.1 Display RGB (DPI) Interface Timing



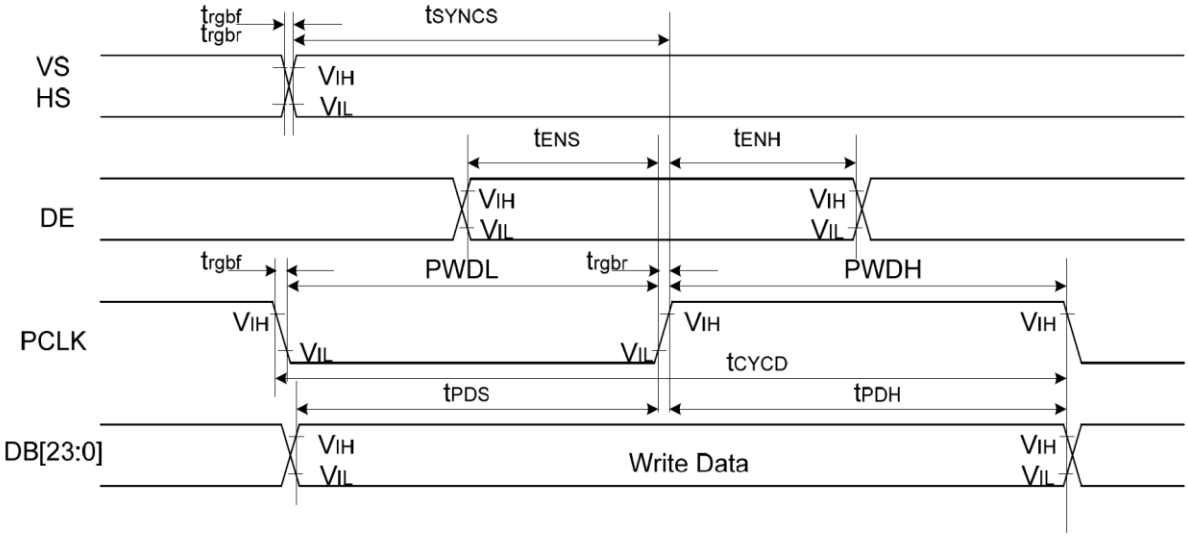
VLW : VSYNC Low pulse Width
HLW : HSYNC Low pulse Width
DTST : Data Transfer Startup Time
Pn : pixel 1, pixel 2⋯, pixel n.

Parameter	Symbols	Min.	Typ.	Max.	Units
Frame Rate	FR	54		66	fps
Horizontal Low Pulse width	HLW	1		-	DOTCLK
Horizontal Back Porch	HBP	2		126	DOTCLK
Horizontal Address	HACT		480		DOTCLK
Horizontal Front Porch	HFP	2		-	DOTCLK
Vertical Low Pulse width	VLW	1		126	Line
Vertical Back Porch	VBP	1		126	Line
Vertical Address	VACT			864	Line
Vertical Front Porch	VFP	1		255	Line
Data Clock	DCLK	16.6		41.7	MHz

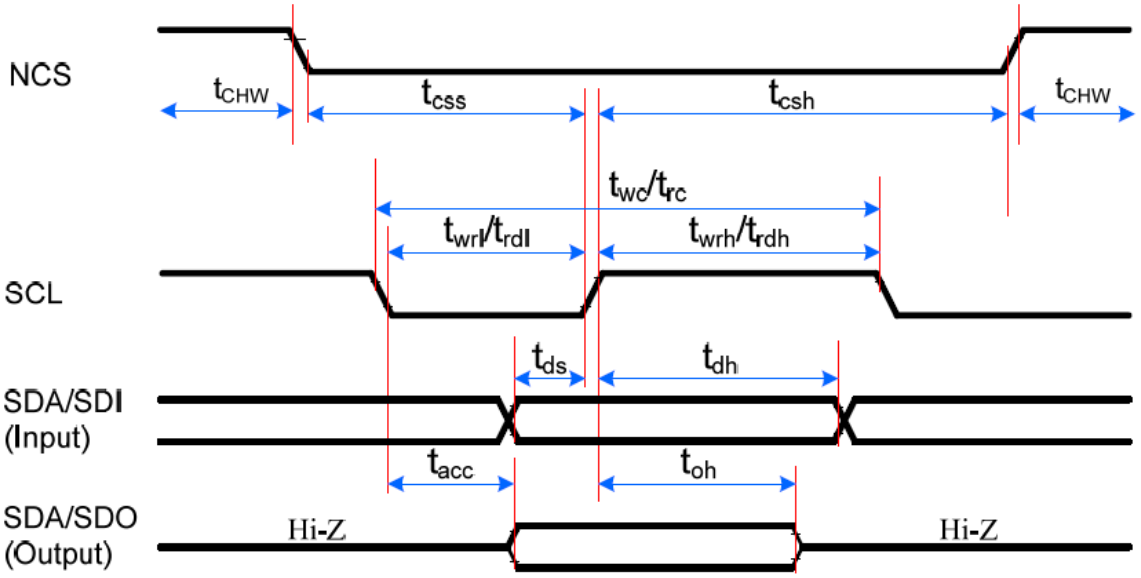
3.4.2 Display Parallel RGB (24/18/16 bit) DPI Interface Timing

Signal	Symbol	Parameter	min	max	Unit	Description
VS/ HS	tSYNCS	VS/HS setup time	5	-	ns	24/18/16-bit bus RGB interface mode
	tSYNCH	VS/HS hold time	5	-	ns	
DE	tENS	DE setup time	5	-	ns	
	tENH	DE hold time	5	-	ns	
DB[23:0]	tPOS	Data setup time	5	-	ns	
	tPDH	Data hold time	5	-	ns	
PCLK	PWDH	PCLK high-level period	13	-	ns	
	PWDL	PCLK low-level period	13	-	ns	
	tCYCD	PCLK cycle time	28	-	ns	
	trgbr , trgbf	PCLK,HS,VS rise/fall time	-	15	ns	

Note: Ta=-20 to 70C, VCI=2.5V to 3.6V, GND=0V



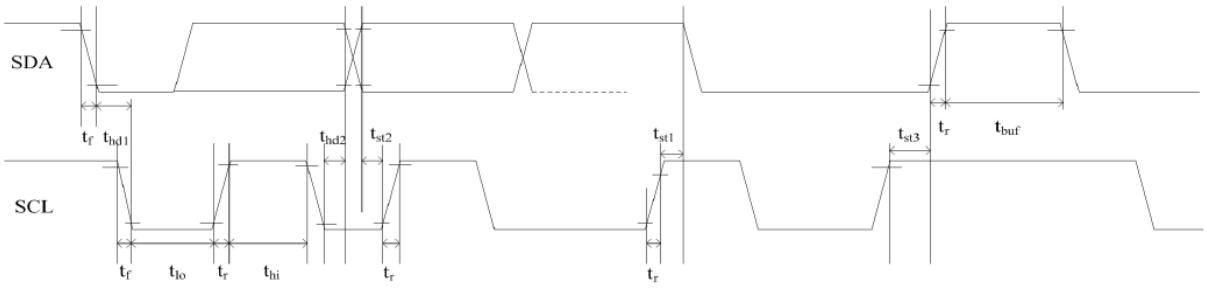
3.4.3 Display Serial interface Timing characteristics (3-line SPI System)



Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tcss	Chip select time (Write)	15	-	ns	
	tcsh	Chip select hold time (Read)	15	-	ns	
	tCHW	CS "H" pulse width	40	-	ns	
SCL	twc	Serial clock cycle (Write)	30	-	ns	
	twrh	SCL "H" pulse width (Write)	10	-	ns	
	twrl	SCL "L" pulse width (Write)	10	-	ns	
	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
SDA/SDO (Output)	tacc	Access time (Read)	10	100	ns	For maximum CL=30pF
	toh	Output disable time (Read)	15	100	ns	For minimum CL=8pF
SDA/SDI (Input)	tds	Data setup time (Write)	10	-	ns	
	tdh	Data hold time (Write)	10	-	ns	

3.4.4 PCT I2C Interface Timing

GT911 provides a standard I2C interface for SCL and SDA to communicate with the host. GT911 always serves as slave device in the system with all communication being initialized by the host. It is strongly recommended that transmission rate be kept at or below 400Kbps. The I2C timing is shown below:



Test condition 1: 1.8V host interface voltage, 400Kbps transmission rate, 2K pull-up resistor

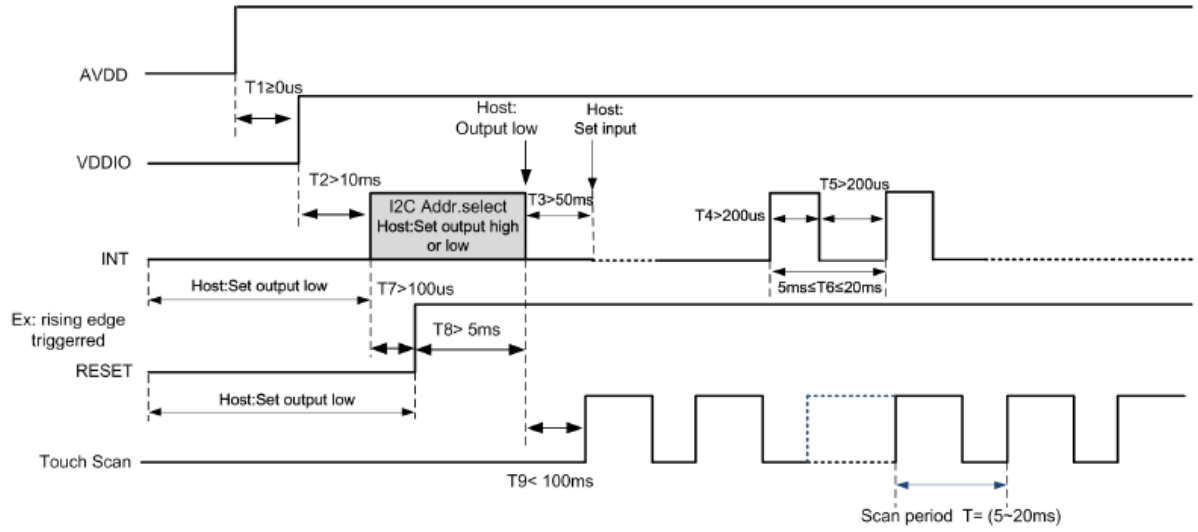
Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

Test condition 2: 3.3V host interface voltage, 400Kbps transmission rate, 2K pull-up resistor

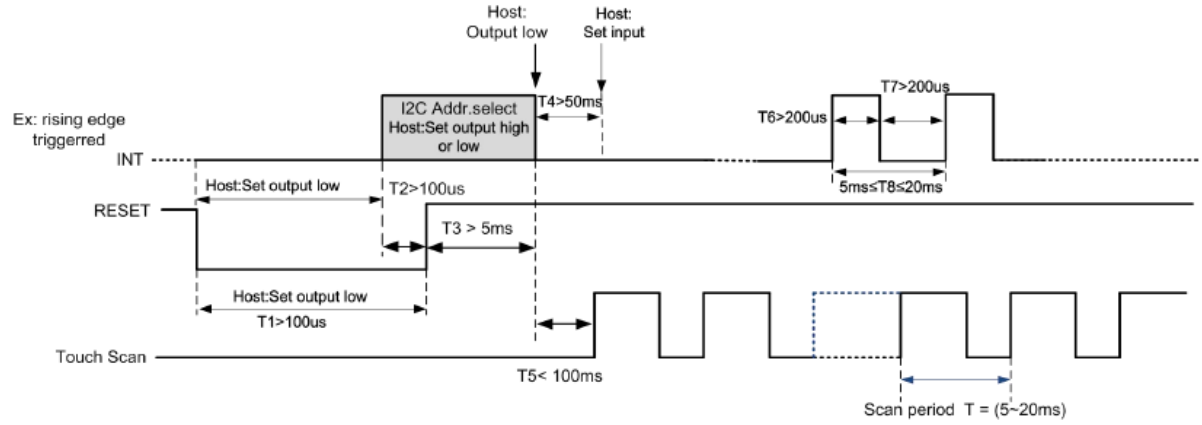
Parameter	Symbol	Min.	Max.	Unit
SCL low period	t_{lo}	1.3	-	us
SCL high period	t_{hi}	0.6	-	us
SCL setup time for Start condition	t_{st1}	0.6	-	us
SCL setup time for Stop condition	t_{st3}	0.6	-	us
SCL hold time for Start condition	t_{hd1}	0.6	-	us
SDA setup time	t_{st2}	0.1	-	us
SDA hold time	t_{hd2}	0	-	us

GT911 supports two I2C slave addresses: 0XBA/0Xbb and 0x28/0x29. The host can select the address by changing the status of Reset and INT pins during the power-on initialization phase. See the diagram below for configuration methods and timings:

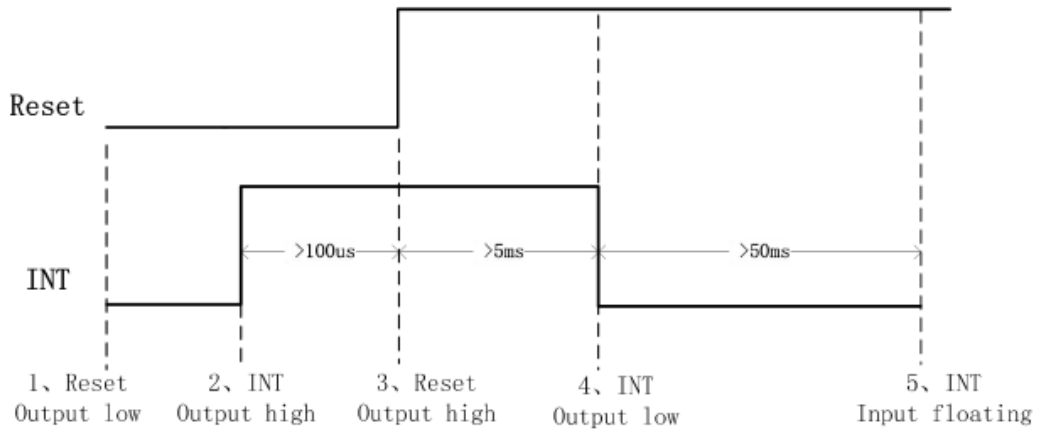
Power-On Timing:



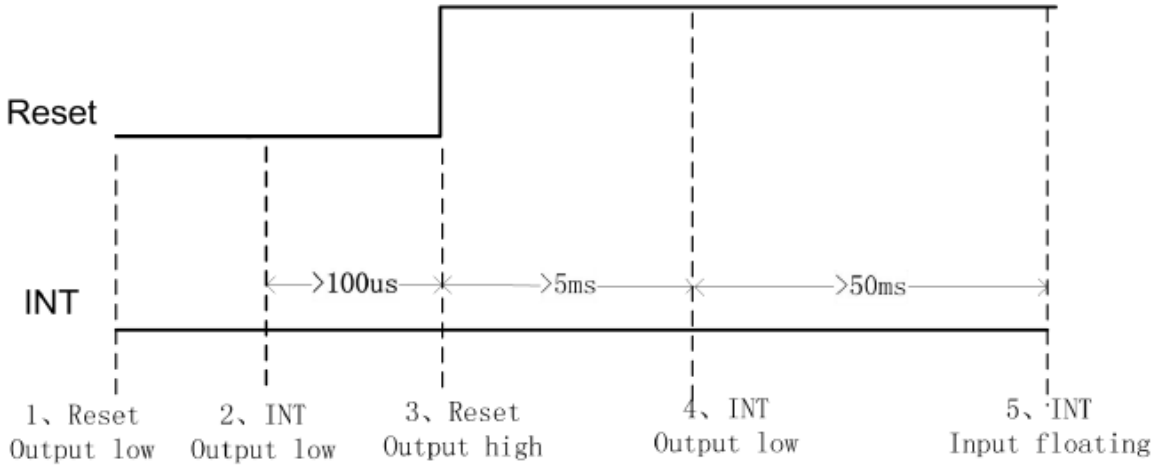
Timing for host resetting GT911:



Timing for setting slave address to 0x28/0x29:



Timing for setting slave address to 0XBA/0XBB:



A) Data Transmission

(For example：device address is 0xBA/0xBB)

Communication is always initiated by the host. Valid Start condition is signalled by pulling SDA line from “high” to “low” when SCL line is “high”. Data flow or address is transmitted after the Start condition.

All slave devices connected to I2C bus should detect the 8-bit address issued after Start condition and send the correct ACK. After receiving matching address, GT911 acknowledges by configuring SDA line as output port and pulling SDA line low during the ninth SCL cycle. When receiving unmatched address, namely, not 0XBA or 0XBB, GT911 will stay in an idle state.

For data bytes on SDA, each of 9 serial bits will be sent on nine SCL cycles. Each data byte consists of 8 valid data bits and one ACK or NACK bit sent by the recipient. The data transmission is valid when SCL line is “high”.

When communication is completed, the host will issue the STOP condition. Stop condition implies the transition of SDA line from “low” to “high” when SCL line is “high”.

B) Writing Data to GT911

(For example: device address is 0XBA/0xBB)

Timing for Write Operation

The diagram above displays the timing sequence of the host writing data onto GT911. First, the host issues a Start condition. Then, the host sends 0XBA (address bits and R/W bit; R/W bit as 0 indicates Write operation) to the slave device.

After receiving ACK, the host sends the 16-bit register address (where writing starts) and the 8-bit data bytes (to be written onto the register).

The location of the register address pointer will automatically add 1 after every Write Operation. Therefore, when the host needs to perform Write Operations on a group of registers of continuous addresses, it is able to write continuously. The Write Operation is terminated when the host issues the Stop condition.

C) Reading Data from GT911
(For example: device address is 0xBA/0xBB)

Timing for Read Operation

The diagram above is the timing sequence of the host reading data from GT911. First, the host issues a Start condition and sends 0XBA (address bits and R/W bit; R/W bit as 0 indicates Write operation) to the slave device.

After receiving ACK, the host sends the 16-bit register address (where reading starts) to the slave device. Then the host sets register addresses which need to be read.
Also after receiving ACK, the host issues the Start condition once again and sends 0XBB (Read Operation). After receiving ACK, the host starts to read data.

GT911 also supports continuous Read Operation and, by default, reads data continuously. Whenever receiving a byte of data, the host sends an ACK signal indicating successful reception. After receiving the last byte of data, the host sends a NACK signal followed by a STOP condition which terminates communication.

3.5 POWER SEQUENCE

3.5.1 RESET Input Timing

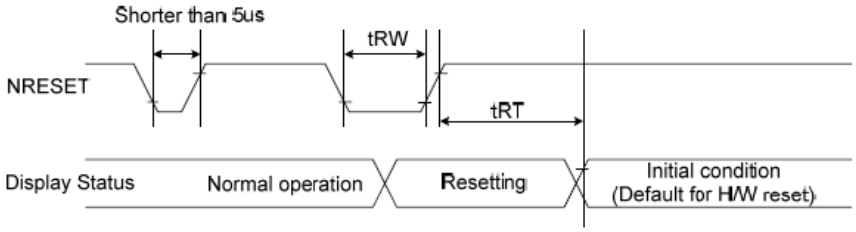


Figure 102 Reset Timing

Table 41 Reset Timing

Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		us
	tRT	Reset cancel		5(note 1,5)	ms
				120 (note 1,6,7)	ms

Note:

1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from OTP to registers. This loading is done every time when there is H/W reset cancel time (tRT) within 5 ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the Table 43.

Table 42 Reset Descript

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out mode. The display remains the blank state in Sleep In mode.) and then return to Default condition for Hardware Reset.
4. Spike Rejection also applies during a valid reset pulse as shown below:

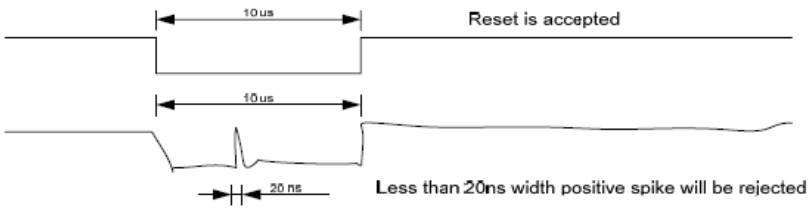


Figure 103 Positive Noise Pulse during Reset Low

5. When Reset applied during Sleep In Mode.
6. When Reset applied during Sleep Out Mode.
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

3.5.2 Power on/off Sequence

Please refer to IC ILI9806E datasheet.

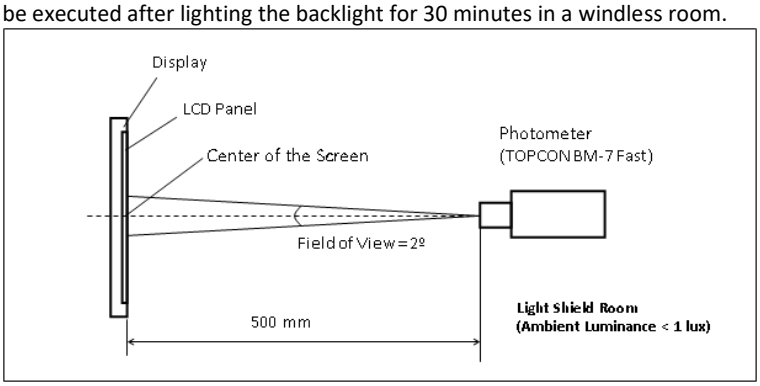
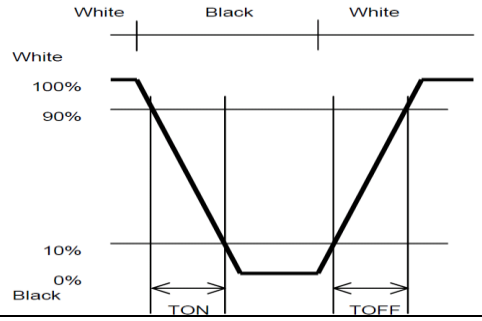
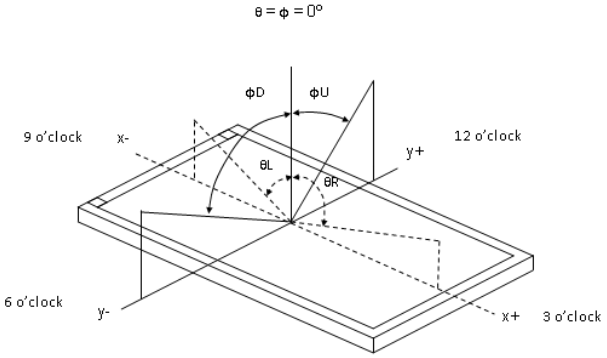
4 OPTICAL SPECIFICATION

4.1 OPTICAL CHARACTERISTICS

Driving condition: VCI = 3.3V, VSS = 0V
Backlight: IF=40mA
Measured temperature: Ta ＝ 25˚C

Item		Symbol	Condition	MIN	TYP	MAX	Unit	Note
Response Time		TR+TF	θ=Φ=0° Normal Viewing Angle	-	30	35	ms	2
Contrast Ratio		CR		640	800	-		3
Viewing Angle	Left	θL	CR ≥ 10	-	80	-	deg	4
	Right	θR		-	80	-	deg	
	Up	ϕU		-	80	-	deg	
	Down	ϕD		-	80	-	deg	
Colour Chromaticity	Red	Rx	CR ≥ 10	-	0.659	-	-	5
		Ry		-	0.322	-	-	
	Green	Gx		-	0.290	-	-	
		Gy		-	0.588	-	-	
	Blue	Bx		-	0.134	-	-	
		By		-	0.124	-	-	
	White	Wx		-	0.305	-	-	
		Wy		-	0.340	-	-	
Centre Brightness			If=40mA	430	470	-	cd/m²	6
Brightness Distribution				80	-	-	%	7

4.1.1 Test Method

Note	Item	Test method
1	Setup	The display should be stabilised at a given temperature for 30 minutes to avoid abrupt temperature change during measuring. In order to stabilise the luminance, measurements should be executed after lighting the backlight for 30 minutes in a windless room. 
2	Response time	Measure output signal waveform by the luminance meter when raster of window pattern is changed from white to black and from black to white. 
3	Contrast ratio	Measure maximum brightness and minimum brightness at the centre of the screen by displaying raster or window pattern. Then calculate the ratio between these two values. Contrast Ratio (CR) = $\frac{\text{Brightness of unselected position (white)}}{\text{Brightness of selected position (black)}}$
4	Viewing angle Horizontal θ Vertical Ø	Move the luminance meter from right to left and up and down and determinate the angles where contrast ratio is 10 
5	Colour chromaticity	Measure chromaticity coordinates x and y of CIE1931 colorimetric system
6	Centre brightness	Measure the brightness at the centre of the screen
7	Brightness distribution	(Brightness distribution)= 100 x B/A % A: max. brightness of the 9 points B: min. brightness of the 9 points

5 BACKLIGHT SPECIFICATION

5.1 LED DRIVING CONDITIONS

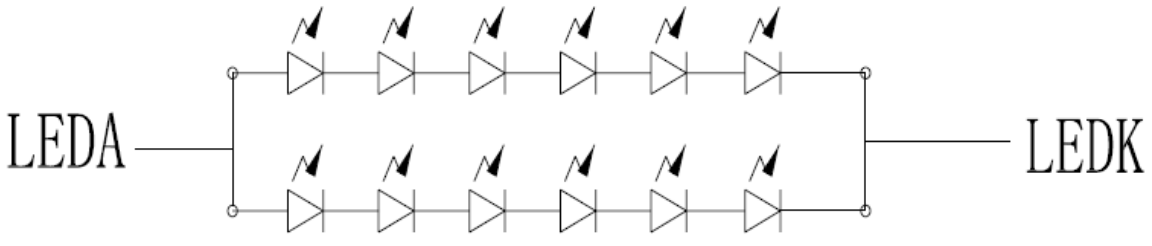
The back light system is edge-lighting type with 12 chips White LED

Item	Symbol	Condition	Min	Typ	Max	Unit
Forward Current	IF	Ta=25 °C,	30	40	-	mA
Forward Voltage	VF	Ta= 25°C,		19.2		V
LED life time	Hr	Ta= 25°C,	-	-	50000	Hour

Note:

- The lifetime of the LED is defined as a period till the brightness of the LED decreases to the half of its initial value.
- This figure is given as a reference purpose only, and not a guarantee.
- This figure is estimated for an LED operating alone.
  The performance of an LED may differ when assembled as a monitor together with a TFT panel due to different environmental temperature.
- Estimated lifetime could vary on a different temperature and usually higher temperature could reduce the life significantly.

5.2 LED CIRCUIT



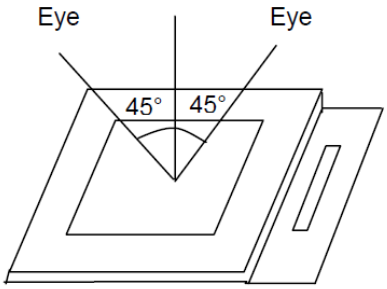
CIRCUIT DIAGRAM

6 QUALITY ASSURANCE SPECIFICATION

6.1 DELIVERY INSPECTION STANDARDS

6.1.1 Inspection Conditions

Inspection distance: 30 cm ± 2 cm
Viewing angle: ±45°



6.1.2 Environmental Conditions

Ambient temperature: 25°C ±5°C
Ambient humidity: 65±10% RH
Ambient illumination: 300~700 lux

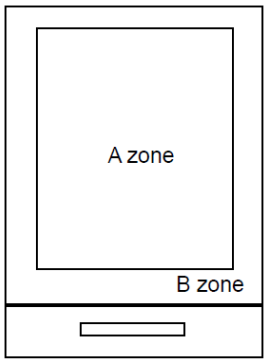
6.1.3 Sampling Conditions

1. Lot size: quantity of shipment lot per model
2. Sampling method:

Sampling Plan		GB/T 2828-2003
		Normal inspection, Single Sampling, ClassⅡ
AQL	Major Defect	0.65%
	Minor Defect	1.5%

6.1.4 Definition of Area

A zone: active area
B zone: viewing area

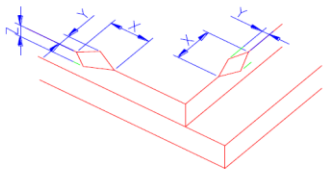
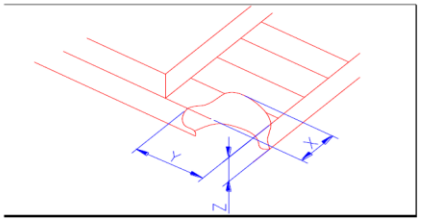
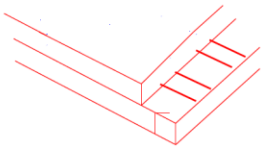


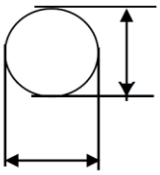
6.1.5 Basic Principle

A set of sample to indicate the limit of acceptable quality level shall be discussed should a dispute occur.

6.1.6 Inspection Criteria

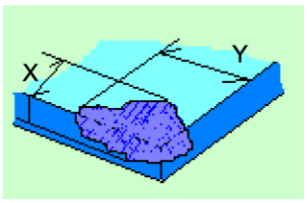
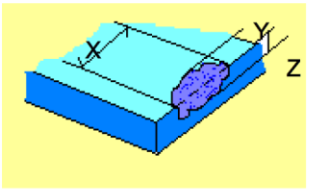
<table>
<tr><th>Number</th><th>Items</th><th>Criteria(mm)</th></tr>
<tr><td rowspan="3">1.0 LCD Crack/Broken

NOTE:
X: Length
Y: Width
Z: Height
L: Length of ITO,
T: Height of LCD</td><td>(1) The edge of LCD broken</td><td> 
<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr></table></td></tr>
<tr><td>(2)LCD corner broken</td><td> 
<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table></td></tr>
<tr><td>(3) LCD crack</td><td> 
Crack
Not allowed</td></tr>
</table>

<table>
<tr><th>Number</th><th>Items</th><th>Criteria (mm)</th></tr>
<tr><td>2.0</td><td>Spot defect
 
X
Φ=(X+Y)/2</td><td>① light dot (LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain)
<table>
<tr><th rowspan="2">Zone
Size (mm)</th><th colspan="3">Accep able Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.10</td><td colspan="2">Ignore</td><td rowspan="4">Ignor</td></tr>
<tr><td>0.10<Φ≤0.20</td><td colspan="2">3(distance≧10mm)</td></tr>
<tr><td>0.20<Φ≤0.25</td><td colspan="2">2</td></tr>
<tr><td>Φ > 0.25</td><td colspan="2">0</td></tr>
</table>
②Dim spot (LCD/TP/Polarizer dim dot, light leakage、dark spot)
<table>
<tr><th rowspan="2">Zone
Size (mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.1</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.10<Φ≤0.20</td><td colspan="2">3(distance≧10mm)</td></tr>
<tr><td>0.20<Φ≤0.30</td><td colspan="2">2</td></tr>
<tr><td>Φ > 0.30</td><td colspan="2">0</td></tr>
</table>
③ Polarizer accidented spot
<table>
<tr><th rowspan="2">Zone
Size (mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.2</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.3<Φ≤0.5</td><td colspan="2">2(distance≧10mm)</td></tr>
<tr><td>Φ>0.5</td><td colspan="2">0</td></tr>
</table></td></tr>
<tr><td></td><td>Line defect (LCD/TP /Polarizer black/white line, scratch, stain)</td><td>
<table>
<tr><th rowspan="2">Width(mm)</th><th rowspan="2">Length(mm</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.03</td><td>Ignoe</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.03<W≤0.05</td><td>L≤3.0</td><td colspan="2">N≤2</td></tr>
<tr><td>0.05<W≤0.08</td><td>L≤2.0</td><td colspan="2">N≤2</td></tr>
<tr><td>0.08<W</td><td colspan="4">Define as spot defect</td></tr>
</table></td></tr>
</table>

<table>
<tr><td>3.0</td><td>Polarizer Bubble</td><td>
<table>
<tr><td rowspan="2">Zone
Size (mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.2</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.2<Φ≤0.4</td><td colspan="2">3(distance≧10 m)</td></tr>
<tr><td>0.4<Φ≤0.6</td><td colspan="2">2</td></tr>
<tr><td>0.6<Φ</td><td colspan="2">0</td></tr>
</table>
</td></tr>
<tr><td>4.0</td><td>SMT</td><td>According to IPC-A-610C class Ⅱ standard . Function defect and missing part are major defect ,the others are minor defect.</td></tr>
</table>

<table>
<tr><td rowspan="2"></td><td rowspan="2"></td><td>TP bubble/ accidented spot</td><td>
<table>
<tr><td rowspan="2">Size Φ(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.1</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.1<Φ≤0.25</td><td colspan="2"></td></tr>
<tr><td>0.25<Φ≤0.3</td><td colspan="2">2</td></tr>
<tr><td>0.3<Φ</td><td colspan="2">0</td></tr>
</table>
</td></tr>
<tr><td>Assembly deflection</td><td>beyond the edge of backlight ≤0.15mm</td></tr>
</table>

<table>
<tr><td>5.0</td><td>TP Related</td><td>Newton Ring</td><td>Newton Ring area>1/3 TP area NG
Newton Ring area≤1/3 TP area OK</td><td>  </td></tr>
<tr><td></td><td></td><td>TP corner broken
X : length
Y : width
Z : height</td><td><table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>X≤3.0mm</td><td>Y≤3.0mm</td><td>Z<LCD thickness</td></tr></table>*
Circuitry broken is not allowed.</td><td>  </td></tr>
<tr><td></td><td></td><td>TP edge broken
X : length
Y : width
Z : height</td><td><table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>X≤6.0mm</td><td>Y≤2.0mm</td><td>Z<LCD thickness</td></tr></table>* Circuitry broken is not allowed.</td><td>  </td></tr>
</table>

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

6.1.7 Classification of Defects

Visual defects (except no or wrong label) are treated as minor defects, while electrical defects are treated as major defects.
Two minor defects are equal to one major defect in lot sampling inspection.

6.1.8 Identification / Marking criteria

Any unit with illegible / wrong / double or no marking / label shall be rejected.

6.2 DEALING WITH CUSTOMER COMPLAINTS

6.2.1 Non-conforming analysis

Purchaser should supply Densitron with detailed data of non-conforming sample.
After accepting it, Densitron should complete the analysis in two weeks from receiving the sample.
If the analysis cannot be completed on time, Densitron must inform the purchaser.

6.2.2 Handling of non-conforming displays

If any non-conforming displays are found during customer acceptance inspection which Densitron is clearly responsible for, return them to Densitron.
Both Densitron and customer should analyse the reason and discuss the handling of non-conforming displays when the reason is not clear.
Equally, both sides should discuss and come to agreement for issues pertaining to modification of Densitron quality assurance standard.

7 RELIABILITY SPECIFICATION

7.1 RELIABILITY TESTS

Test Item		Test Condition	
Durability Test	High Temperature Storage	Ta= 80˚C	96h
	Low Temperature Storage	Ta=-30˚C	96h
	Temperature Cycle Storage	-20°C ←→ 70°C ON/OFF, 20 cycles. ON time over 10 seconds ,OFF time over 10 seconds	
	High Temperature Operation	Tp= 70°C	96h
	Low Temperature Operation	Tp= -20°C	96h
	High Temperature & Humidity Operation	Tp= 70°C RH= 90% 96h Non condensing	
	ESD Test	150Pf, 330Ω, ±6KV (Contact)/±8KV (Air), 5 Points/panel, 10 times/point	
	Thermal Shock Resistance	The sample should be allowed to stand the following 5 cycles of operation: TSTL for 30 minutes -> normal temperature for 5 minutes -> TSTH for 30 minutes -> normal temperature for 5 minutes, as one cycle, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours	
	Box Drop Test	1 Corner 3 Edges 6 faces, 66 cm (Medium Box)	

Note: Ta=ambient temperature Tp= Panel temperature

Notes:
1. No dew condensation to be observed.
2. The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.
3. No cosmetic or functional defects should be allowed.
4. Total current consumption should be less than twice the initial value.

8 HANDLING PRECAUTIONS

Safety

If the LCD panel breaks, be careful not to get the liquid crystal fluid in your mouth or in your eyes. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and plenty of water.

Mounting and Design

Place a transparent plate (e.g. acrylic, polycarbonate or glass) on the display surface to protect the display from external pressure. Leave a small gap between the transparent plate and the display surface.

When assembling with a zebra connector, clean the surface of the pads with alcohol and keep the surrounding air very clean.

Design the system so that no input signal is given unless the power supply voltage is applied.

Caution during LCD cleaning

Lightly wipe the display surface with a soft cloth soaked with Isopropyl alcohol, Ethyl alcohol or Trichlorotriflorothane.

Do not wipe the display surface with dry or hard materials that will damage the polariser surface.

Do not use aromatic solvents (toluene and xylene), or ketonic solvents (ketone and acetone).

Caution against static charge

As the display uses C-MOS LSI drivers, connect any unused input terminal to VDD or VSS. Do not input any signals before power is turned on. Also, ground your body, work/assembly table and assembly equipment to protect against static electricity.

Packaging

Displays use LCD elements, and must be treated as such. Avoid strong shock and drop from a height. To prevent displays from degradation, do not operate or store them exposed directly to sunshine or high temperature/humidity.

Caution during operation

It is indispensable to drive the display within the specified voltage limit since excessive voltage shortens its life. Direct current causes an electrochemical reaction with remarkable deterioration of the display quality. Give careful consideration to prevent direct current during ON/OFF timing and during operation. Response time is extremely delayed at temperatures lower than the operating temperature range while, at high temperatures, displays become dark. However, this phenomenon is reversible and does not mean a malfunction or a display that has been permanently damaged. If the display area is pushed on hard during operation, some graphics will be abnormally displayed but returns to a normal condition after turning off the display once. Even a small amount of condensation on the contact pads (terminals) can cause an electro-chemical reaction which causes missing rows and columns. Give careful attention to avoid condensation.

Storage

Store the display in a dark place where the temperature is 25°C ± 10°C and the humidity below 50%RH. Store the display in a clean environment, free from dust, organic solvents and corrosive gases.

Do not crash, shake or jolt the display (including accessories).